



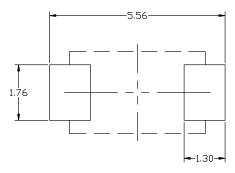
SMA 2.60x4.30x1.00 CASE 403AA ISSUE A

DATE 18 JAN 2024

NOTES:

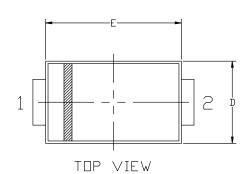
- DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. FL

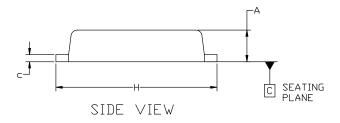
MILLIMETERS					
DIM	MIN	NDM	MAX		
Α	0.90	1.00	1.10		
Ø	1.25	1.45	1.65		
\cup	0.15	0.225	0.30		
D	2.40	2.60	2,80		
П	4.00	4.30	4.60		
Н	4.80	5.10	5.40		
L	0.70	0.90	1.10		

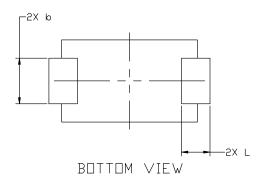


RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference manual, SDLDERRM/D.







GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

A = Assembly Location

Y = Year

WW = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	SMA 2.60x4.30x1.00		PAGE 1 OF 1

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